IPC ASSOCIATION CONNECTINE ELECTRONICS INDUSTRIE	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.				This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lowel level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.												
752-21.1	IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Form Typ Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater						terials and M	ials and Mfg Information					
Supplier Inform	nation																
Company name* Company uniqu				rique ID			Unique ID Authority					Respon	Response Date*				
nsemi													2023-06-07				
Contact Name		Title - Contact			I	Phone - Contact*					Email -	Email - Contact*					
Product-Env-Stewa	ards	Product Enviro Compliance				NA					Produc	Product-Env-Stewards@onsemi.com					
uthorized Represe	entative*	Title - Representative			I	Phone - Representative*				Email -	Email - Representative*						
Product-Env-Stewards			Product Enviro Compliance				NA					Produc	Product-Env-Stewards@onsemi.com				
Requeste	r Item Number Mfr Item Number NCV8752AMX		n Number Mfr Item Name				Effective Da	ate V	ersion	sion Manufact			Weig	ht*	UOM	Unit Type	
			52AMX18TC	C 200 mA LDO, Ultra-Low IQ, Ultra-Low Noise, PG delay 2us			2023-06-07		MY1			3.64		mg	Each		
Ianufacturing	Proccess Informatio	n															
Terminal	l Plating / Grid Array Material		Terminal Base Alloy		J-STD-020 MSI	020 MSL Rating		Peak Process Body Temperature		ure Ma	x Time at Po	eak Tempera	ture	Number	of Reflow Cyc	les	
Precious metal (e.g. Ag,Au, NiPdAu) (no Sn)			CU Alloy 1		1		260		С		30 seco		nds	3			
Comments																	
vel 1 - maximum t	ime at peak temperature	during so	ldering is 10-3	0 seconds													
or more informati	on regarding material cor	nposition	please refer to	page 3													

RoHS Material Composition Declaration			Declaration Type *	Detail	ed						
Directive 2015/863/EU amending RoHS Directive 2011/65/EU RoHS Definition: Quantity limit of 0.01% by mass (100 PPM) in homogeneous material for Cadmium and quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury (Hg), Hexavalent Chromium (Cr6+), Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE), and Bis(2-ethylhexyl) phthalate (DEHP), Benzyl-butyl phthalate (BBP), Dibutyl phthalate (DBP), Diisobutyl phthalate (DIBP).											
Please indicate whether any homogeneous material (as defined by the RoHS Directive, EU 2011/65/EU and implemented by the laws of the European Union member states) of the part identified on this form contains lead, mercury, cadmium, hexavalentchromium, polybrominated biphenyls and/or polybrominated diphenyl ethers (each a "RoHS restricted substance") in excess of the applicable quantity limit identified above. If a homogeneous material within the part contains a RoHS restricted substance inexcess of an applicable quantity limit, please indicate below which, if any, RoHS exemption you believe may apply. If the part is an assembly with lower level components, the declaration shall encompass all such components. Supplier certifies that it gathered the information is true and correction this form. Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products with European Union member state laws that implement the RoHS Directive. Company acknowledges that Supplier may have relied on informationprovided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part, and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier have provided as part of that agreement, will be the sole and exclusivesource of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form. In the absence of such written agreement, the warranty rights and/or remedies of Supplier's Standard Terms and Conditions of Sale applicable to such part shall apply.											
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted						
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.											
Exemption List Version	EL-2011/534/EU										
Declaration Signature											
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the						

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Die	0.25	mg	Supplier	Silicon (Si)	7440-21-3		0.25	mg
Die Attach	0.18	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.108	mg
			Supplier	Aluminum Trioxide (Al2O3)	1344-28-1		0.072	mg
Lead Frame	1.9	mg	Supplier	Tin (Sn)	7440-31-5		0.0047	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0042	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0047	mg
			Supplier	Copper (Cu)	7440-50-8		1.8863	mg
Mold Compound-Black	1.27	mg		Epoxy resin	proprietary data		0.0889	mg
			Supplier	Phenolic Resin	Proprietary Data		0.0889	mg
			Supplier	Silica Amorphous (SiO2)	7631-86-9		0.1905	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0063	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		0.8953	mg
Plating	0.03	mg	Supplier	Palladium (Pd)	7440-05-3		0.0007	mg
			В	Nickel (Ni)	7440-02-0		0.0264	mg
			Supplier	Gold (Au)	7440-57-5		0.0028	mg
Wire Bond - Au	0.01	mg	Supplier	Gold (Au)	7440-57-5		0.01	mg